

Title (en)  
THERMALLY-INSULATED MODULES AND RELATED METHODS

Title (de)  
WÄRMEISOLIERTE MODULE UND ZUGEHÖRIGE VERFAHREN

Title (fr)  
MODULES THERMIQUEMENT ISOLÉS ET PROCÉDÉS ASSOCIÉS

Publication  
**EP 3706608 A1 20200916 (EN)**

Application  
**EP 18874700 A 20181106**

Priority  
• US 201762581966 P 20171106  
• US 201862658022 P 20180416  
• US 2018059478 W 20181106

Abstract (en)  
[origin: WO2019090345A1] Provided are thermally insulated modules that comprise a first shell and a first component having a first sealed evacuated insulating space therebetween and a current carrier configured to give rise to inductive heating. Also provided are methods of utilizing the disclosed thermally insulated modules in a variety of applications, including additive manufacturing and other applications.

IPC 8 full level  
**A47J 41/02** (2006.01); **A47J 36/36** (2006.01); **B65D 81/38** (2006.01)

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